IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						terials and M	ials and Mfg Information				
Supplier Inforn	nation																
Company name*				Company unique ID			Unique ID Authority					Respons	Response Date*				
onsemi												2024-05	2024-05-11				
Contact Name		Title - Contact			1	Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
Authorized Represe	Title - Representative			1	Phone - Representative*				Email -	Email - Representative*							
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
Request	er Item Number	Item Number Mfr Iten		em Number Mfr Item Name			Effective Da	ate V	te Version Ma		Manufacturing Site		Weig	ht*	UOM	Unit Type	
	FDMC809		097AC FET 150V Dual N & P Ch		N & P Channel	MLP33	2024-05-11	TH2				21.5509		mg	Each		
Ianufacturing	Proccess Informati	on															
Terminal	l Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	MSL Rating		Peak Process Body Temperature		ure Ma	ire Max Time at Peak Temper		ature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С	30 sec		secon	nds	3			
Comments																	
evel 1 - maximum	time at peak temperatur	e during so	ldering is 10-3	30 seconds													
or more informati	on regarding material c	omposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.055	mg	Supplier	Silicon (Si)	7440-21-3		1.055	mg
Die Attach	0.1359	mg	Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.001	mg
			Supplier	Isobornyl Methacrylate	7534-94-3		0.0074	mg
			Supplier	Silver (Ag)	7440-22-4		0.1127	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0074	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0074	mg
Lead Frame	9.565	mg	Supplier	Zinc (Zn)	7440-66-6		0.0119	mg
			Supplier	Iron (Fe)	7439-89-6		0.2247	mg
			Supplier	Copper (Cu)	7440-50-8		9.3205	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0079	mg
Mold Compound-Black	10.3333	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5684	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0207	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.7808	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.4467	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5167	mg
Plating	0.1337	mg	Supplier	Silver (Ag)	7440-22-4		0.0021	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0048	mg
			В	Nickel (Ni)	7440-02-0		0.1241	mg
			Supplier	Gold (Au)	7440-57-5		0.0027	mg
Wire Bond - Cu	0.328	mg	Supplier	Copper (Cu)	7440-50-8		0.328	mg